



Physical Interfaces & Carriers Japan TC Chapter

Meeting Summary and Minutes

Japan Summer Meetings 2024

Friday, April 12, 2024, 13:00-15:00 (JST)

SEMI Japan office (via OVTCCM) Hybrid

TC Chapter Announcements

Next TC Chapter Meeting

Friday 13:00-15:00 July 19th, 2024 (Japan Standard Time) at Board Room, SEMI Japan Office + OVTCCM

Table 1 Meeting Attendees

Italics indicate virtual participants

Co-Chairs: Nagashima Tsuyoshi (Miraial), Daisuke Sado (DAIHEN), Yasuhisa Ito (MURATA MACHINERY)

SEMI Staff: Hirofumi Kanno

<i>Company</i>	<i>First</i>	<i>Last</i>	<i>Company</i>	<i>First</i>	<i>Last</i>
Acteon NEXT LLC	Shoji	Komatsu	Miraial Co., Ltd.	Tsuyoshi	Nagashima
DAIHEN Corporation	Daisuke	Sado	MURATA MACHINERY, LTD.	Yasuhisa	Ito
DISCO Corporation	Shinobu	Gonsui	Shin-Etsu Polymer Co., Ltd.	Satoshi	Odashima
Hirata Corporation	Noriyoshi	Toyoda	SINFONIA TECHNOLOGY CO., LTD.	Atsushi	Suzuki
Hirata Corporation	Keiji	Kanazawa	SINFONIA TECHNOLOGY CO., LTD.	Taisuke	Matsukubo
Intel Corporation	Takashi	Shimizu	SINFONIA TECHNOLOGY CO., LTD.	Yasushi	Taniyama
KOKUSAI ELECTRIC CORPORATION	Mitsuhiro	Matsuda	SEMI Japan	Hirofumi	Kanno
Marubeni Plax Corporation	Luke	Igeta			

Table 2 Leadership Changes

<i>WG/TF/SC/TC Name</i>	<i>Previous Leader</i>	<i>New Leader</i>
None		

Table 3 TC Chapter Structure Changes

<i>Previous WG/TF/SC Name</i>	<i>New WG/TF/SC Name or Status Change</i>
None	

Table 4 Ballot Results

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
7170	Line-Item Revision to SEMI E184 -1221E Specification for 300 mm Tape Frame FOUP Load Port	
L1	Addition of E185 Tape Frame FOUP standard to reference section	Pass as balloted
L2	Bias term correction and editorial correction	Pass as balloted
7171	Line-Item Revision to SEMI E185 -1222 Specification for 300 mm Tape Frame FOUP	
L1	Addition of E184 Loadport standard to reference section	Pass as balloted
L2	Correction of z0 calculation mistake	Pass as balloted
L3	Correction of EE Exclusion volume	Pass as balloted
L4	Bias term correction	Pass as balloted

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 5 Ratification Ballot Results

<i>Document #</i>	<i>Document Title</i>	<i>ISC A&R Action</i>	<i>A&R Forms</i>
None			

Note 1: **Passed** Ratification ballots will be submitted to SEMI publication for final processing.

Note 2: **Failed** Ratification ballots were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 6 Activities Approved by the GCS between meetings of the TC Chapter

<i>#</i>	<i>Type</i>	<i>SC/TF/WG</i>	<i>Details</i>
None			

Table 7 Authorized Activities

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

<i>#</i>	<i>Type</i>	<i>SC/TF/WG</i>	<i>Details</i>
None			

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:

<http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF>

Table 8 Authorized Ballots

<i>#</i>	<i>When</i>	<i>TF</i>	<i>Details</i>
None			

Table 9 SNARF(s) Granted a One-Year Extension

<i>#</i>	<i>TF</i>	<i>Title</i>	<i>Expiration Date</i>
None			



Table 10 SNARF(s) Cancelled

#	TF	Title
None		

Table 11 Standard(s) to receive Inactive Status

Standard Designation	Title
None	

Table 12 New Action Items

Item #	Assigned to	Details
20240416-1	SEMI Japan	SEMI staff will report any SNARFs that are expiring this year at the next committee meeting.

Table 13 Previous Meeting Action Items

Item #	Assigned to	Details
None		

1 Welcome, Reminders, and Introductions

Yasuhisa Ito (MURATA MACHINERY) called the meeting to order at 13:00. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: 01, Required Element Nov 2022_E+J (new template)

2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

Motion: Shoji Komatsu / Acteon NEXT LLC

By / 2nd: Daisuke Sado / DAIHEN Corporation

Discussion: Fix the Company name ,Shin-Etsu Handotai Co., Ltd., to Shin Etsu Polymer and change Suzuki-san/Intel to Shimizu-san/Intel.

Vote: 9-Y 0-N Voting Result: Pass - 100.00%. Voting Rule: Majority

Attachment: 02, PIC Mins_20231214

3 Liaison Reports

3.1 PI&C North America TC Chapter

Hirofumi Kanno (SEMI Japan) reported for the TC Chapter as attached slides.

Attachment: 03 NA PIC Liaison Report Mar2024 v1

3.2 SEMI Staff Report

Hirofumi Kanno (SEMI Japan) gave the SEMI Staff Report. Of note:

Attachment: 04 Staff Report March 2024 v4

4 Ballot Review

NOTE 1: TC Chapter adjudication on ballots reviewed is detailed in the Audits & Review (A&R) Subcommittee Forms for procedural review. The A&R forms are available as attachments to these minutes. The attachment number for each balloted document is provided under each ballot review section below.

4.1 Document #7170, Line-Item Revision to SEMI E184-1221E SPECIFICATION FOR

4.1.1 Line Item #1: Addition of E185 Tape Frame FOUP standard to reference section → Pass as balloted

4.1.2 Line Item #2: Bias term correction and editorial correction → Pass as balloted

Attachment: 05 Doc.7170_Ballot Line-Item report_HK

4.2 Document #7171, Line-Item Revision to SEMI E185 -1222 Specification for 300 mm Tape Frame FOUP

4.2.1 Line Item #1: Addition of E184 Loadport standard to reference section → Pass as balloted

4.2.2 Line Item #2: Correction of z0 calculation mistake → Pass as balloted

4.2.3 Line Item #3: Correction of EE Exclusion volume → Pass as balloted

4.2.4 Line Item #4: Bias term correction → Pass as balloted

Attachment: 06 Doc.7171_Ballot Line-Item report HK

5 Subcommittee and Task Force Reports

5.1 *Global PIC Standards Maintenance TF*

No update

5.2 Japan Electron Microscopy Workflow liaison TF

Mr. Komatsu reported that the report is the same as the one that fits the NA Liaison Report.

5.3 Panel Level Packaging Panel FOUP TF

Mr. Komatsu reported as the slides.

Attachment: 07, Panel FOUP TF report_20240412

5.4 Next Gen Assembly / Test Material Handling TF

Mr. Shimizu informed that the next TF meeting will be announced to all parties concerned after the middle of May.

5.5 [Liaison: 3D Packaging & Integration JA TC Chapter] Panel Level Packaging Glass Carrier TF

If there were any attendees today who participated in this task force, they would be in a position to report, but since they were not present, the meeting was skipped.

5.6 [Liaison: 3D Packaging & Integration NA TC Chapter] Panel Level Packaging Panel TF



If there were any attendees today who participated in this task force, they would be in a position to report, but since they were not present, the meeting was skipped.

6 Old Business

6.1 Project Period Review

Action Item: SEMI staff will report any SNARFs that are expiring this year at the next committee meeting. (SEMI Staff)

6.2 5 Year Review

Mr. Komatsu will confirm at SEMICON West.

7 New Business

None

8 Next Meeting and Adjournment

The next meeting is scheduled for July 19th, 2024, 13:00-15:00 at Board Room, SEMI Japan Office. See <http://www.semi.org/standards-events> for the current list of events.

Adjournment: 16:00

Respectfully submitted by:

Hirofumi Kanno

Sir Manger, Standards & EHS

SEMI Japan

Email: hkanno@semi.org

Minutes tentatively approved by:

Nagashima Tsuyoshi (Miraial)	<Date approved>
Daisuke Sado (DAIHEN)	
Yasuhisa Ito (MURATA MACHINERY)	<Date approved>

Table 14 Index of Available Attachments^{#1}

<i>Title</i>	<i>Title</i>
01 Required Element Nov 2022_E+J (new template)	02 PIC Mins_20231214_HK
03 NA PIC Liaison Report Mar2024 v1	04 Staff Report March 2024 v4
05 Doc.7170_Ballot Line-Item report_HK	06 Doc.7171_Ballot Line-Item report HK
07 Panel FOUP TF report_20240412	

^{#1} Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.